

INTERNATIONAL STANDARD

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Semiconductor devices – Flexible and stretchable semiconductor devices –
Part 2: Evaluation method for electron mobility, sub-threshold swing, and
threshold voltage of flexible devices

Dispositifs à semiconducteurs – Dispositifs à semiconducteurs souples et
extensibles –

Partie 2: Méthode d'évaluation pour la mobilité des électrons, la pente en régime
de sous-seuil et la tension de seuil des dispositifs souples



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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**SEMICONDUCTOR DEVICES –
FLEXIBLE AND STRETCHABLE SEMICONDUCTOR DEVICES –****Part 2: Evaluation method for electron mobility, sub-threshold swing, and
threshold voltage of flexible devices****FOREWORD**

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Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

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The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

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- withdrawn,
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SEMICONDUCTOR DEVICES – FLEXIBLE AND STRETCHABLE SEMICONDUCTOR DEVICES –

Part 2: Evaluation method for electron mobility, sub-threshold swing, and threshold voltage of flexible devices

1 Scope

This part of IEC 62951 specifies terms, definitions, symbols, configurations and evaluation methods that can be used to evaluate and determine the performance characteristics of flexible thin-film transistor (TFT) devices. This document specifies test methods and characteristic parameters for accurately evaluating the performance and reliability in practical use of flexible TFT devices under the bending status.

2 Normative references

There are no normative references in this document.

3 Terms and definitions

For the purposes of this document, the following terms and definitions apply.

ISO and IEC maintain terminological databases for use in standardization at the following addresses:

- IEC Electropedia: available at <http://www.electropedia.org/>
- ISO Online browsing platform: available at <http://www.iso.org/obp>

3.1

flexible thin-film transistor

flexible TFT

thin-film transistor fabricated on mechanically flexible substrates such as polymers and metal foils

Note 1 to entry: This note applies to the French language only.

3.2

mobility

<of an electron> quantity equal to the quotient of the modulus of the mean velocity of a charge carrier (electron) in the direction of an electric field by the modulus of the field strength

[SOURCE: IEC 60050-521:2002, 521-02-58, modified — "electron" has been added.]

3.3

sub-threshold swing

S

parameter for quantifying how sharply the transistor is turned off by the gate voltage, defined by the following formula

$$S = \ln(10) \frac{kT}{q} \left(1 + \frac{C_d}{C_{ox}}\right)$$